

# PATENT ABSTRACTS OF JAPAN

(11)Publication number : 05-021909

(43)Date of publication of application : 29.01.1993

(51)Int.Cl.

H05K 1/02

H05K 3/00

(21)Application number : 03-172533

(71)Applicant : MATSUSHITA ELECTRIC IND CO  
LTD

(22)Date of filing : 12.07.1991

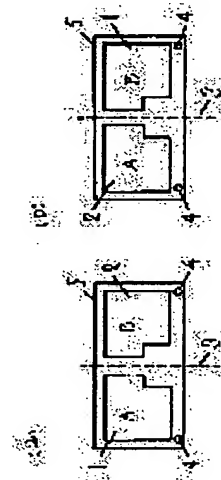
(72)Inventor : YOSHIDA FUMIAKI

## (54) MULTIPLY BEVELED SUBSTRATE

(57)Abstract:

PURPOSE: To rationalize a manufacturing process, and to reduce manufacturing cost by improving the arrangement of printed wiring boards regarding a multiple beveled substrate, in which a large number of the printed wiring boards are arranged on one substrate.

CONSTITUTION: Mutually the same electronic components are mounted on the mounting surfaces A of printed wiring boards 1, 2, and mutually the same components are also mounted similarly on mounting surfaces B. These printed wiring boards 1, 2 are linearly symmetrized centering around symmetry axes 3 on substrates 5, and arranged so that the mounting surfaces A, B are positioned on the surfaces and rears of the substrates 5 respectively. When the substrates are reversed centering around the symmetry axes 3, the mounting surfaces, on which the same electronic components are mounted, in the opposed printed wiring boards are positioned.



## LEGAL STATUS

[Date of request for examination] 11.03.1997

[Date of sending the examiner's decision of rejection] 10.11.1998

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office